

ABSTRACT OF THE DISCLOSURE

A lead-free solder includes at least one selected from 0.01 to 1% by weight of Co, 0.01 to 0.2% by weight of Fe, 0.01 to 0.2% by weight of Mn, 0.01 to 0.2% by weight of Cr, and 0.01 to 2% by weight of Pd; 0.5 to 2% by weight of Cu; and 90.5% by weight or more of Sn. This solder exhibits a satisfactory solderability in solder joints and shows a high resistance to electrode leaching upon soldering or when the resulting soldered article is left at high temperatures.

10087786-07502